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TIDA-01230 REV A Bill of Materials



Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	!PCB	1		TIDA-01230	Any	Printed Circuit Board	
2	C1, C2	2	10uF	GRM21BR6YA106KE43L	MuRata	CAP, CERM, 10 μF, 35 V, +/- 10%, X5R, 0805	0805
3	C3, C4, C5, C6,	8	0.1uF	GRM155R71E104KE14D	MuRata	CAP, CERM, 0.1 μF, 25 V, +/- 10%, X7R, 0402	0402
	C7, C8, C9, C10						
4	J1, J2	2		M22-2510605	Harwin	Header, 2mm, 6x1, Gold, TH	Header, 2mm, 6x1,
							TH
5	R2, R4, R5, R6,	5	0	ERJ-1GE0R00C	Panasonic	RES, 0, 5%, 0.05 W, 0201	0201
	R7						
6	R3	1	10.0k	ERJ-2RKF1002X	Panasonic	RES, 10.0 k, 1%, 0.1 W, 0402	0402
7	U1	1		ISOW7842DWR	Texas Instruments	ISOW7842DW, DW0016B	DW0016B
8	U2	1		TRS3122ERGER	Texas Instruments	RS-232 (2 - 2) TRANSCEIVER WITH SPLIT SUPPLY PIN FOR LOGIC	RGE0024H
						SIDE, RGE0024H	
9	R1	0	0	ERJ-1GE0R00C	Panasonic	RES, 0, 5%, 0.05 W, 0201	0201

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